inspur 浪潮

Inspur NF5288M5 AI Supercomputer

"AI Supercomputer" for Intelligent Computing and HPC Application

Product Features

Breakthrough Limit, One Super Feature and Multiple Powerful Features

Ultra-high density. 2U space supports 2×
Intel ® Xeon ® Scalable Processor, 8 × GPU
card on NVIDIA® NVLink ™ or HHHL and
dual-width PCIE GPU card

Excellent performance. 960 Tensor TFLOPs
ensure peak computing capacity, and over
60 TFLOPs peak dual-precision floating point
capability, easily making peak performance
per single case (42U) cluster higher than 1
PFLOPs to deliver optimal computing
capacity to customers.

Flexible Configuration and Varying as Needed

Multiple co-processor options
support Tesla®SXM2 V100/P100
based on NVIDIA® NVLink™, and
V100/P100/P40 GPU and Xeon
Phi based on PCIe3.0 port, etc.

Front panel supports 2x
PCIE3.0x16 slot for HHHL card;
for SXM2 GPU mode, rear panel
supports 4 × PCIE3.0x16 slot for
HHHL card, expanded as needed.

Supports over 10 GPU topologies,
such as low latency, high
bandwidth, balanced computing,
etc., for multiple deep learning or
high performance application
scenarios.

Support cascade mode, allow
GPU longitudinal expansion, and
support up to 16 × GPUs, greatly
improving system efficiency.

NVIDIA®NVLink2.0 allows
300GB/s high-speed bandwidth
between GPU. Hybrid Cube Mesh
reduces the latency of multi-GPU
data sharing, and keep cache
consistency between multiple

GPUs, providing a better acceleration ratio for computing.

Ingenious Design and Green Innovation

1 + 1 redundant 3,000W 80Plus titanium PSU with ultra-low power loss, supplying power to up to 96% high-efficient digital power conversion.

Low-heat front module and high-heat rear module avoid local hot spots. Even

Scale-out Flexibility, Scale-up Efficiency

Support 4 × 100G RDMA, greatly optimizing horizontal expansion capacity.

temperature rise of air-cooled channel and 5 × high-speed fans for heat radiation keep the system operating stably at 35°C room temperature.

Reserve liquid cooling connectors, support air-liquid heat radiation mode, and transfer 80% heat via GPU liquid cooling module, reducing data center PUE significantly.

www.inspur.com

Specification

Model	NF5288M5
Height	2U
CPU	Support 1/2 × new generation Intel ® Xeon ® Scalable Processor, TDP 165W
GPU	**SXM2 GPU board:** Support 8 × NVIDIA® Tesla® NVLink™ V100/P100 NVLink PCIE GPU board: Support 8 × PCIe 3.0 X16 slot Support 8 × FHFL dual-width PCIe V100/P100/P40/Xeon Phi, etc.
Chipset	Intel® C620 series chipset (Lewisburg-4)
Memory	Support 16 DDR4, 2666MHz RDIMM
PCIE card on board	1 × PCIe 3.0 X8 Mezz RAID card on board
Front I/O	2 USB 3.0, 1 VGA port, 2 PCIe 3.0x16 HHHL slot
Rear I/O	1 × RS232 serial port 1 × VGA port 2 × USB 3.0 port 1 × RJ35 management port 4 × 10G SFP+ Internet port 2 × C20 power supply port For SXM2 GPU, provide 4 × PCIe 3.0x16 HHHL slot and reserve liquid cooling port for heat radiation
Storage	Support front 8 × 2.5 inch SAS/SATA hard disk or U.2 NVMe SSD hard disks Support 2 × SATA or PCIe M.2 SSD on board
RAID support	Optional RAID0, 1, 10, 1E, 5, 50, 6 and 60. Support Cache super capacitor protection, and provide RAID state transition and RAID configuration memory
Operating system	Microsoft Windows Sever, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, CentOS, etc.
Radiator system	5 × system fan
PSU	2 × 3,000w 80Plus Titanium PSU, 1+1
Chassis	448mm width, 87.5 mm height, 899.5mm depth
Operating Temperature	5 - 35°C / 41°F - 95°F

Inspur Electronic Information Industry Co., Ltd. (Beijing)

Website: www.inspur.com

Product pictures and words herein are for reference only. Please inquire local dealers for detailed specifications and prices.

Technical support and service hotline: 400-860-0011 or 0531-88546554

Consultation hotline: 400-860-6708 or 800-860-6708 or 0531-88933376

BJ1708-210-285